

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YOSHIKI YAMAMOTO	12/17/2012
HIDEKI MAKIYAMA	12/17/2012
TOSHIAKI IWAMATSU	12/17/2012
TAKAAKI TSUNOMURA	12/22/2012
RECEIVING PARTY DATA	
Name:	RENESAS ELECTRONICS CORPORATION
Street Address:	2-24, TOYOSU 3-CHOME, KOTO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	135-0061
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17224743
CORRESPONDENCE DATA	
Fax Number:	(202)756-8087
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-756-8000
Email:	rfeimster@mwe.com, ipdocketmwe@mwe.com, wdcipptsclerks@mwe.com
Correspondent Name:	TOMOKI TANIDA
Address Line 1:	MCDERMOTT WILL & EMERY LLP
Address Line 2:	500 NORTH CAPITOL STREET, N.W.
Address Line 4:	WASHINGTON, D.C. 20001
ATTORNEY DOCKET NUMBER:	074214-0064
NAME OF SUBMITTER:	RENELL FEIMSTER FOR TOMOKI TANIDA
SIGNATURE:	/Renell Feimster for Tomoki Tanida/
DATE SIGNED:	10/24/2023
Total Attachments: 2 source=Assignment#page1.tif	

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, a corporation organized under the laws of Japan, located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8668, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Yoshiki YAMAMOTO</u> (Yoshiki YAMAMOTO)	<u>December 17, 2012</u>
2) <u>Hideki MAKIYAMA</u> (Hideki MAKIYAMA)	<u>December 17, 2012</u>
3) <u>Toshiaki IWAMATSU</u> (Toshiaki IWAMATSU)	<u>December 17, 2012</u>
4) _____ (Takaaki TSUNOMURA)	_____
5) _____	_____
6) _____	_____

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(譲渡証)

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to be held and enjoyed by said Renesas Electronics Corporation,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) _____ (Yoshiki YAMAMOTO)

2) _____ (Hideki MAKIYAMA)

3) _____ (Toshiaki IWAMATSU)

4) Takaaki Tsunomura (Takaaki TSUNOMURA)

December 22, 2012

5) _____

6) _____
